

IN THE CLAIMS:

Please CANCEL claims 34-37 without prejudice to or disclaimer of the recited subject matter.

Please amend Claims 22-24, 28-33 and add Claims 38-40 as follows. Note that all the claims currently pending in this application, including those not currently amended, have been reproduced below for the Examiner's convenience.

1-21. (Previously Cancelled)

22. (Currently Amended) A pod, which has walls and a lid for an opening formed by said walls, and is capable of including a substrate, said pod being pressed against an electromagnetic-shielded chamber of a device manufacturing apparatus which imports the substrate through an opening of said pod and processes the substrate, said pod comprising:

walls which form the opening;

a lid for the opening; and

an electromagnetic shield member which is provided by said walls, at least a portion of said electromagnetic shield member being provided on said walls so as to contact the electromagnetic-shielded chamber so that said electromagnetic shield member is grounded through the electromagnetic-shielded chamber; and

a flange provided around the opening, which is to contact an electromagnetic-shielded chamber for processing the substrate, at a portion around an opening covered with a lid of the electromagnetic-shielded chamber, and causes said electromagnetic shield member to be

~~grounded through the electromagnetic-shielded chamber.~~

23. (Currently Amended) A pod according to Claim 22, wherein said lid ~~of~~ said pod is arranged in front of said pod.

24. (Currently Amended) A pod according to Claim 22, wherein said lid ~~of~~ said pod is arranged in a bottom of said pod.

25. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises wire mesh provided on or within said walls.

26. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises metal coatings provided on said walls.

27. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises electromagnetic-shield materials provided in said walls.

28. (Currently Amended) ~~A micro-device manufacturing~~ An apparatus for manufacturing a device using a substrate, said apparatus comprising:

an electromagnetic-shielded chamber ~~having an opening covered with a door;~~
~~a door opener which opens said door~~ an importing unit which imports the

substrate through an opening of a pod pressed against said electromagnetic-shielded chamber;

and

a processing system, contained in said electromagnetic-shielded chamber, which processes the substrate; and

~~a stand which mounts a pod, wherein said pod has walls and a lid for an opening formed by said walls, and is capable of including the substrate, said pod comprising:~~

~~(i) an electromagnetic shield member provided by said walls; and~~

~~(ii) a flange provided around the opening of said pod, which is to~~

~~contact said electromagnetic-shielded chamber at a portion around said opening of said electromagnetic-shielded chamber, and causes said electromagnetic shield member to be grounded through said electromagnetic-shielded chamber~~ unit which processes the substrate imported by said importing unit;

wherein a portion, against which the pod is to be pressed, of said electromagnetic-shielded chamber is grounded.

29. (Currently Amended) An apparatus according to claim 28, wherein said electromagnetic-shielded chamber has a grounded portion is provided around said an opening of said electromagnetic-shielded chamber[[],] through which contacts said flange of said pod said importing unit imports the substrate.

30. (Currently Amended) An apparatus according to Claim 28, wherein said processing system unit has a function of exposing exposing the substrate to radiation a pattern.

31. (Currently Amended) An apparatus according to Claim 28, wherein said a lid of said for the opening of the pod is arranged in front of said the pod.

32. (Currently Amended) An apparatus according to Claim 28, wherein said a lid of said for the opening of the pod is arranged in a bottom of said the pod.

33. (Currently Amended) An apparatus according to Claim 28, wherein said an electromagnetic shield member ~~comprises wire mesh~~ is provided ~~on or within said by the walls~~ of the pod.

Claims 34 through 37 are cancelled.

38. (New) A device manufacturing method comprising a step of transferring a substrate using a pod defined in Claim 22.

39. (New) A device manufacturing method comprising a step of processing a substrate using a pod an apparatus defined in Claim 28.

40. (New) A method according to Claim 39, wherein in said processing step, the substrate is exposed to a pattern.